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In the Claims:

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Claims 70-75, 77, 80-83, 85-86 and 89-97 were pending at the time of the
3
Office Action.

4
Claims 89 and 90 were previously withdrawn from consideration.

5
Claims 70-75, 77, 80-83, 85-86 and 91-97 are rejected.

6
Please cancel claims 70-75, 77, 80-83, 85-86 and 91-97.

7
Please add new claims, 98-111, as indicated in the following complete list
8
of claims:

9
Claims 1-88 (Canceled)

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11
12
89. (Withdrawn) A package, comprising:
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an integrated circuit enclosed with the package,
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substantially C-shaped leads at a first end of the package,
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a guide member on a side of the package, wherein the guide member has a
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ramp, and
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mechanical support pins at a second end of the package opposite the first
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end,
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wherein the package resides substantially horizontally with respect to a
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circuit board when the package is inserted in a base assembly coupled to the
21
circuit board.

1 **90.** (Withdrawn) The package of claim 89, wherein the integrated
2 circuit is a dynamic random access memory device.

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4 **Claims 91-97** (Canceled)

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6 **98.** (New) A chip socket assembly comprising:
7 a single chip package configured to house a single integrated circuit chip;
8 a first clip arm extending from a first side of the chip package;
9 a second clip arm extending from a second side of the chip package, the
10 first side and the second side being opposite one another;
11 a plurality of flexible leads, each flexible lead having a length, a first end
12 connected to a third side of the chip package, and a second end disconnected from
13 the third side of the chip package and extending away from the chip package
14 through the length, each flexible lead configured to provide mechanical and
15 electrical connection between the single integrated circuit chip and a circuit board;
16 and
17 an indentation in the chip package into which the second end of the flexible
18 leads are extendable.

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20 **99.** (New) The chip socket assembly of claim 98, wherein the
21 first clip arm and the second clip arm each include a ledge protruding from their
22 ends, the chip socket assembly further comprising:
23 a base for receiving the chip package and facilitating the mechanical and
24 electrical connection between the single integrated circuit chip and the circuit
25 board, the base having a first socket and a second socket for securing the chip

1 package to the base, the first socket configured to receive the ledge of the first clip
2 arm and the second socket configured to receive the ledge of the second clip arm.

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4 **100. (New)** The chip socket assembly of claim 98, wherein the
5 flexible leads are substantially C-shaped.

6

7 **101. (New)** The chip socket assembly of claim 100, wherein the
8 flexible leads are compressible.

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10 **102. (New)** The chip socket assembly of claim 101, wherein the
11 flexible leads extend into the indentation when compressed.

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13 **103. (New)** The chip socket assembly of claim 100, further
14 comprising a flexible insert residing between the flexible leads and the third side
15 of the chip package, wherein the flexible insert supplies spring force when the
16 flexible leads are compressed.

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18 **104. (New)** The chip socket assembly of claim 103, wherein the
19 flexible insert is cylindrical.

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21 **105. (New)** The chip socket assembly of claim 104, wherein the
22 flexible insert is a compliant material.

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24 **106. (New)** The chip socket assembly of claim 105, wherein the
25 compliant material is an elastomer.

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2 **107. (New)** The chip socket assembly of claim 98, wherein the
3 flexible leads comprise beryllium-copper.
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5 **108. (New)** The chip socket assembly of claim 98, wherein the
6 chip package comprises a flexible material.
7

8 **109. (New)** The chip socket assembly of claim 98, wherein the
9 chip package comprises silicone rubber.
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11 **110. (New)** The chip socket assembly of claim 98, wherein the
12 single integrated circuit chip is flexible.
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14 **111. (New)** The chip socket assembly of claim 99, further
15 comprising:
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17 a pin extending from the chip package; and
18 a slotted guide in the base configured to receive the pin and guide the chip
19 package into the base.
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